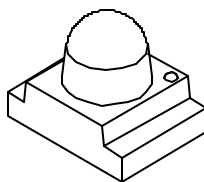
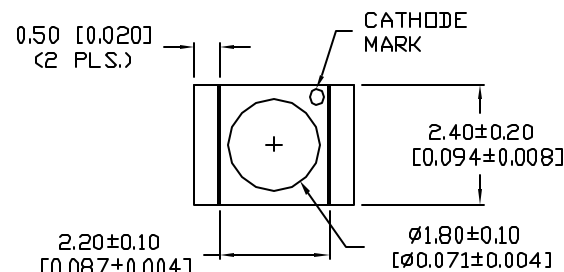
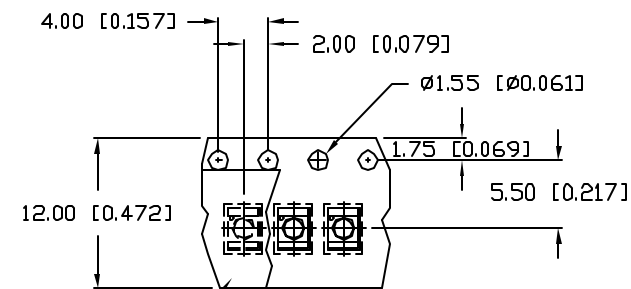
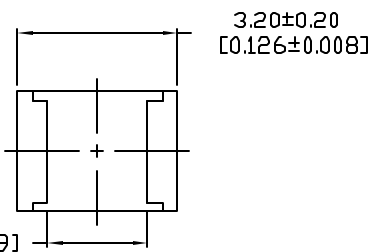
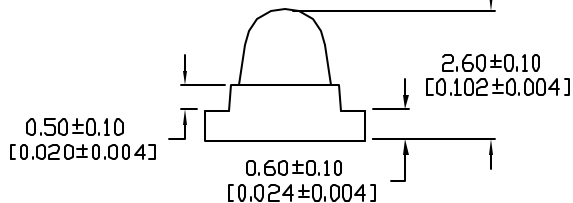


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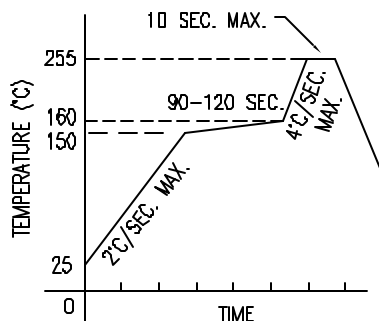


ANODE CATHODE

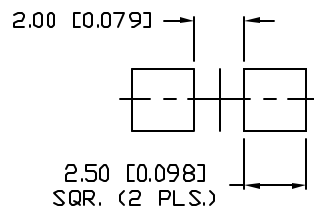


TOP TAPE
TAPE FEED DIRECTION →

LEAD FREE REFLOW PROFILE



RECOMMENDED SOLDER PAD LAYOUT



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+DECIMAL PRECISION -0.00, MAX=+0.00 -DECIMAL PRECISION

PART NUMBER
SML-LXL1209SYC-TR

REV.
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11148.	5.14.07

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		590		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		400		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		50		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



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B

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3.2mm x 2.4mm SURFACE MOUNT LED,
590nm SUPER YELLOW LED,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 11.28.00
			PAGE: 1 OF 1
			SCALE: N/A